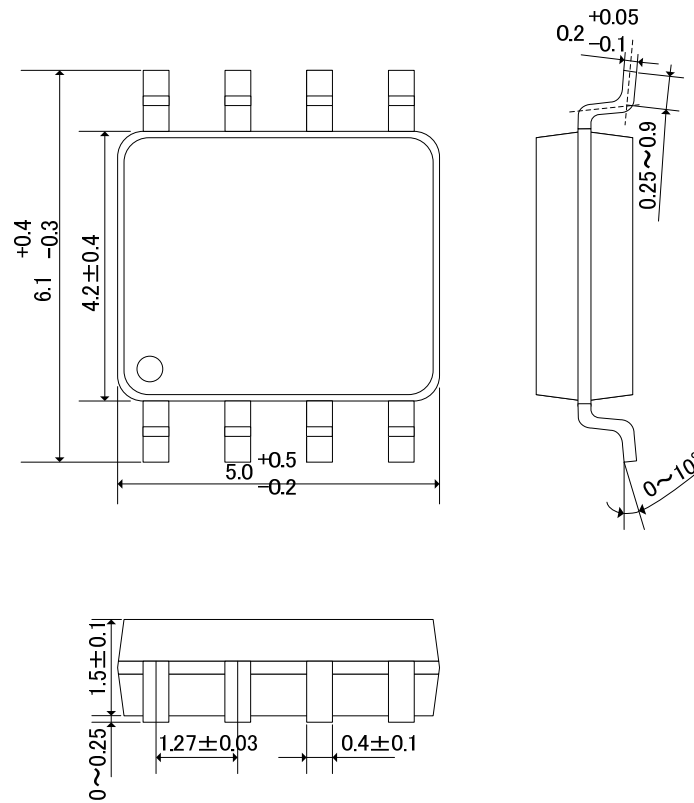


Packaging Information / Reference Pattern Layout Dimensions

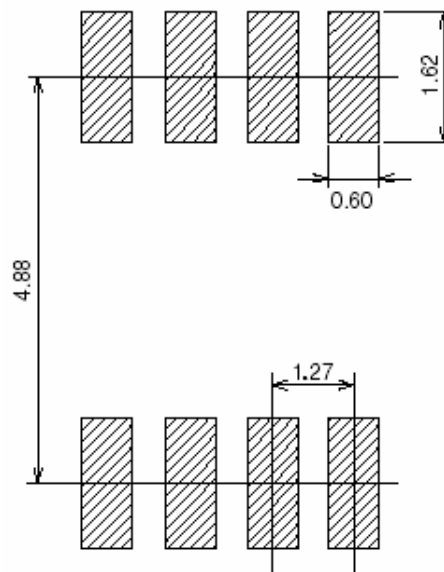
● SOP-8

Unit: mm

■ Packaging Information



■ Reference Pattern Layout Dimension

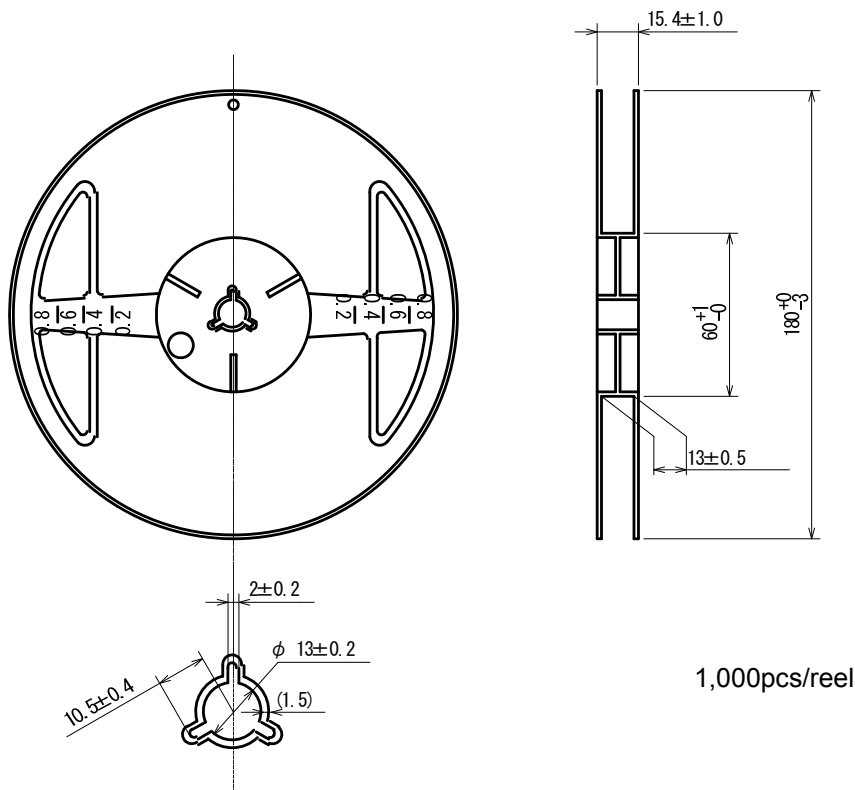


テーピング仕様 / Taping Specifications

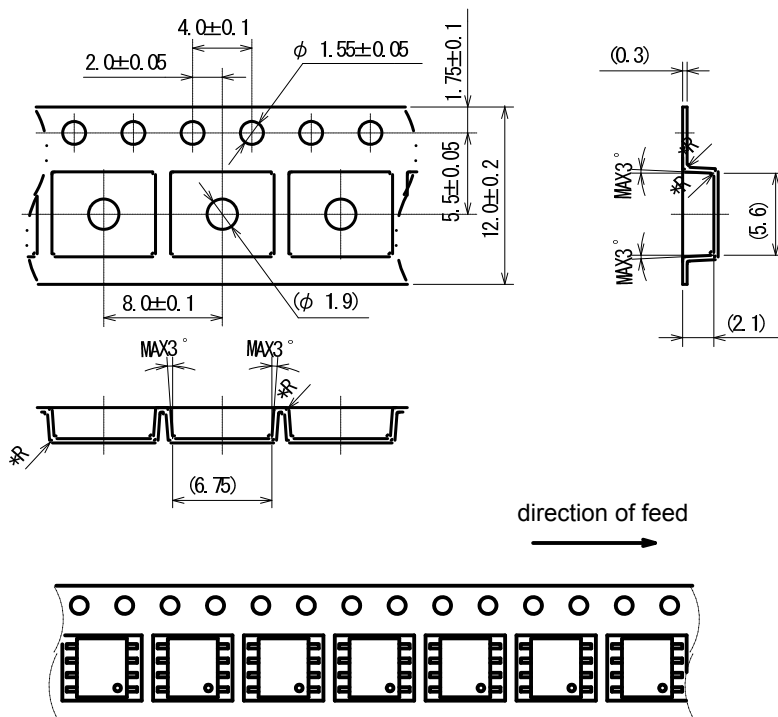
SOP-8

Unit: mm

●リール/Reel



●テーピング仕様/Taping Specifications



R Type : [Device orientation : Right]

Standard feed

**●SOP-8 Power Dissipation**

Power dissipation data for the SOP-8 is shown in this page.

The value of power dissipation varies with the mount board conditions.

Please use this data as one of reference data taken in the described condition.

**1. Measurement Condition (Reference data)**

Condition : Mount on a board

Ambient : Natural convection

Soldering : Lead (Pb) free

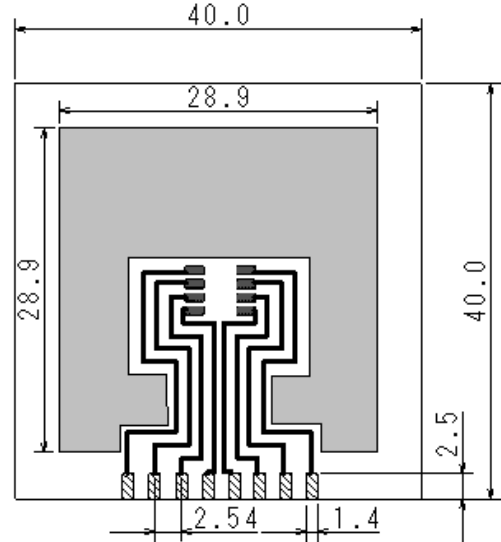
Board : Dimensions 40mm×40mm (1600mm<sup>2</sup> in one side)

Copper (Cu) traces occupy 50% of the board area

In top and back faces

Material : Glass Epoxy (FR-4)

Thickness : 1.6mm

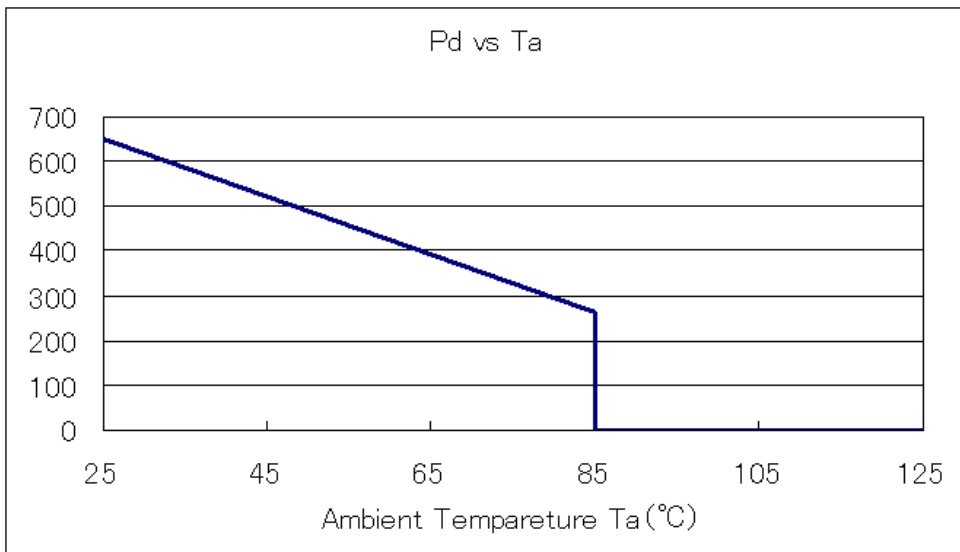


Evaluation Board (Unit: mm)

**2. Power Dissipation vs. Ambient temperature**

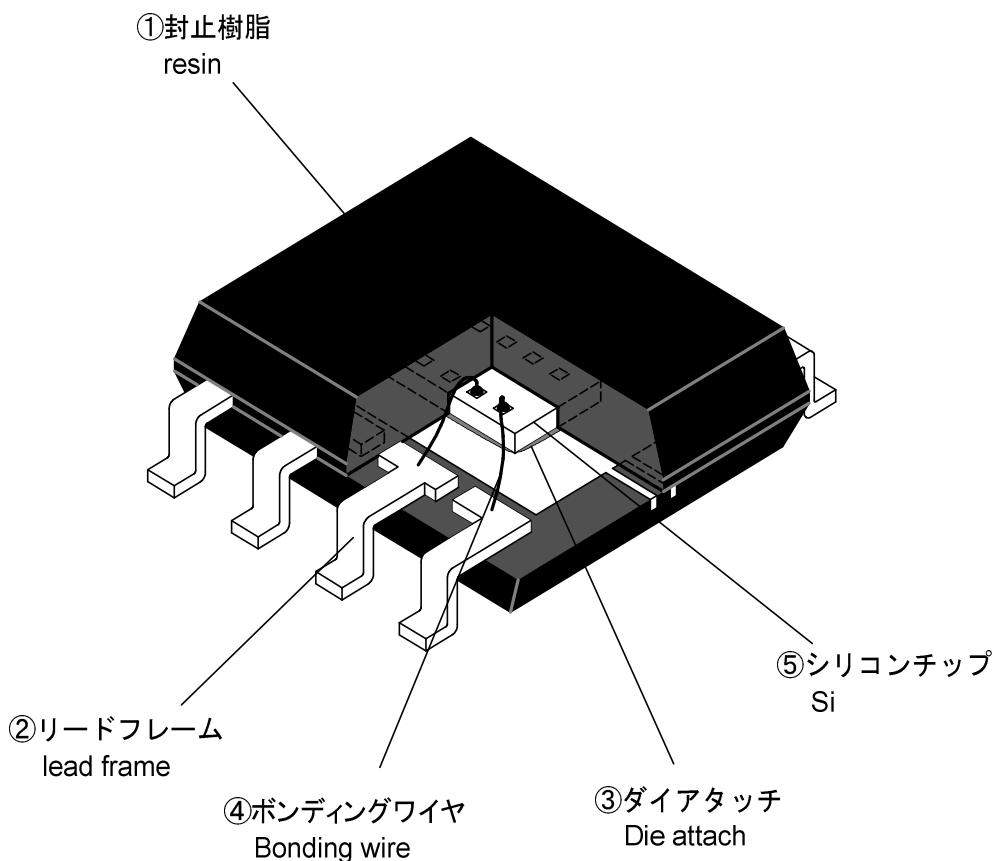
Board Mount ( T<sub>jmax</sub>=125°C)

Ambient Temperature (°C)	Power Dissipation Pd (mW)	Thermal Resistance (°C/W)
25	650	153.85
85	260	



SOP-8構造図  
SOP-8 Perspective

RoHS対応品  
RoHS Compliance



項目 Item	材料 Material	備考 Note
① 封止樹脂 Resin	エポキシ樹脂 Epoxy resin	難燃グレード/Flammability rating UL94V-0
② リードフレーム Lead frame	銅系 Copper alloy	
端子処理 Lead plating	鉛フリーはんだメッキ Lead(Pb) free solder plating	
③ ダイアタッチ Die attach	銀入りエポキシ Silver filled Epoxy	
④ ボンディングワイヤ Bonding wire	Au	
⑤ シリコンチップ Si	Si	

捺印表示 Marking	レーザー Laser marking
-----------------	-----------------------